

Piezoelectric MEMS Energy Harvesters

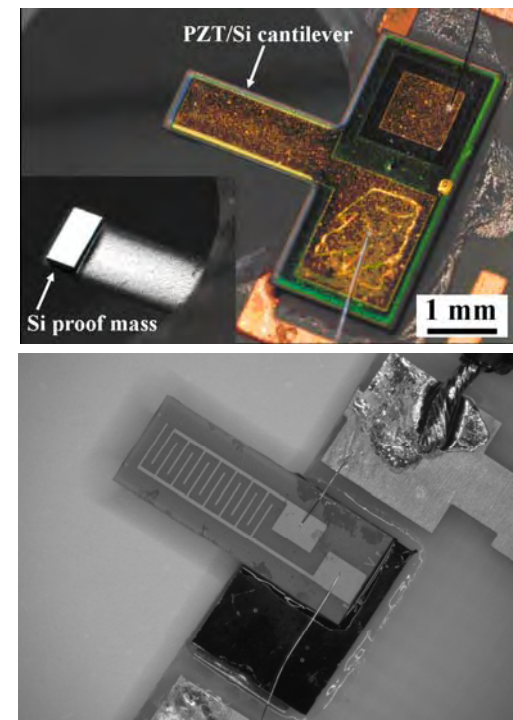
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Team leader EnviroMEMS

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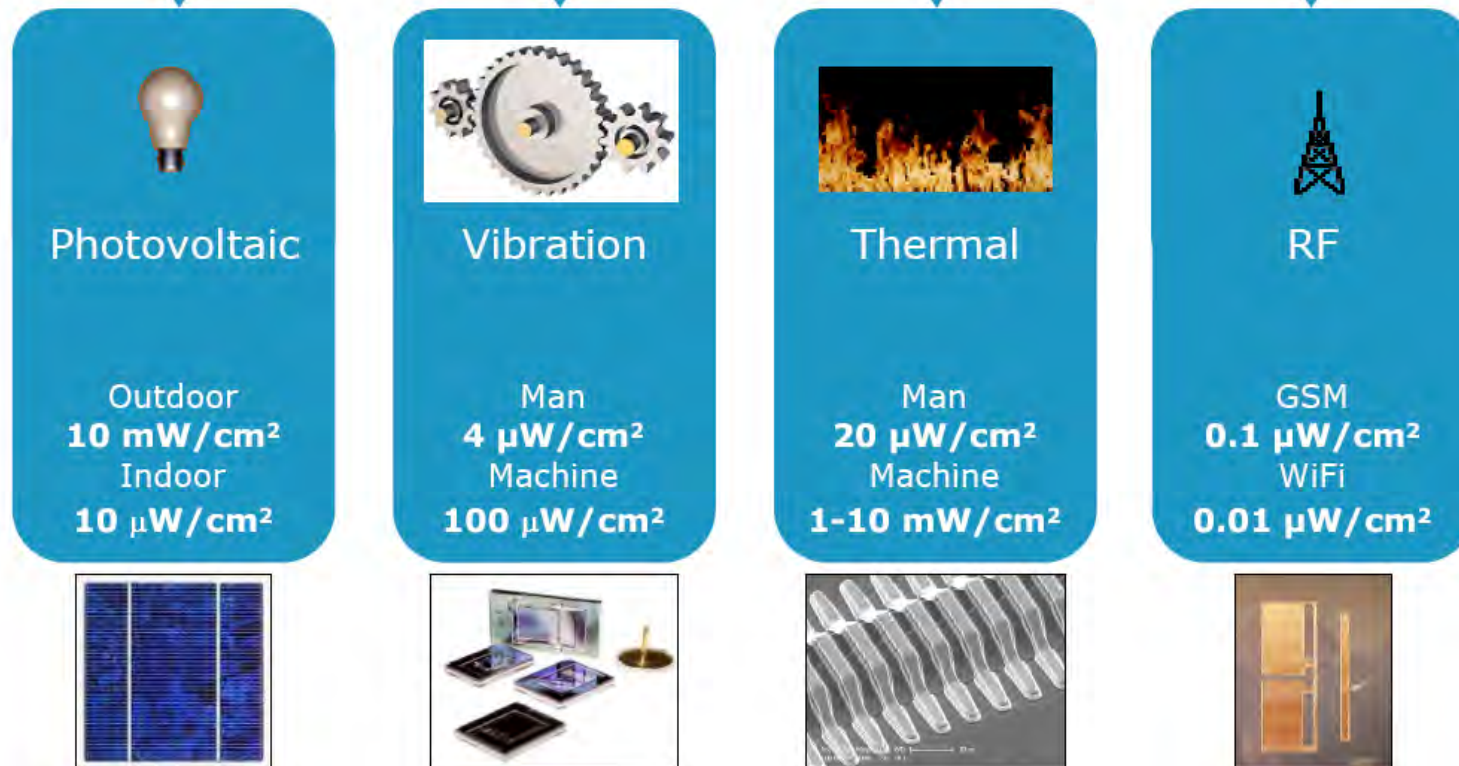
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Sources of energy and harvesting approaches

How much power is available ?

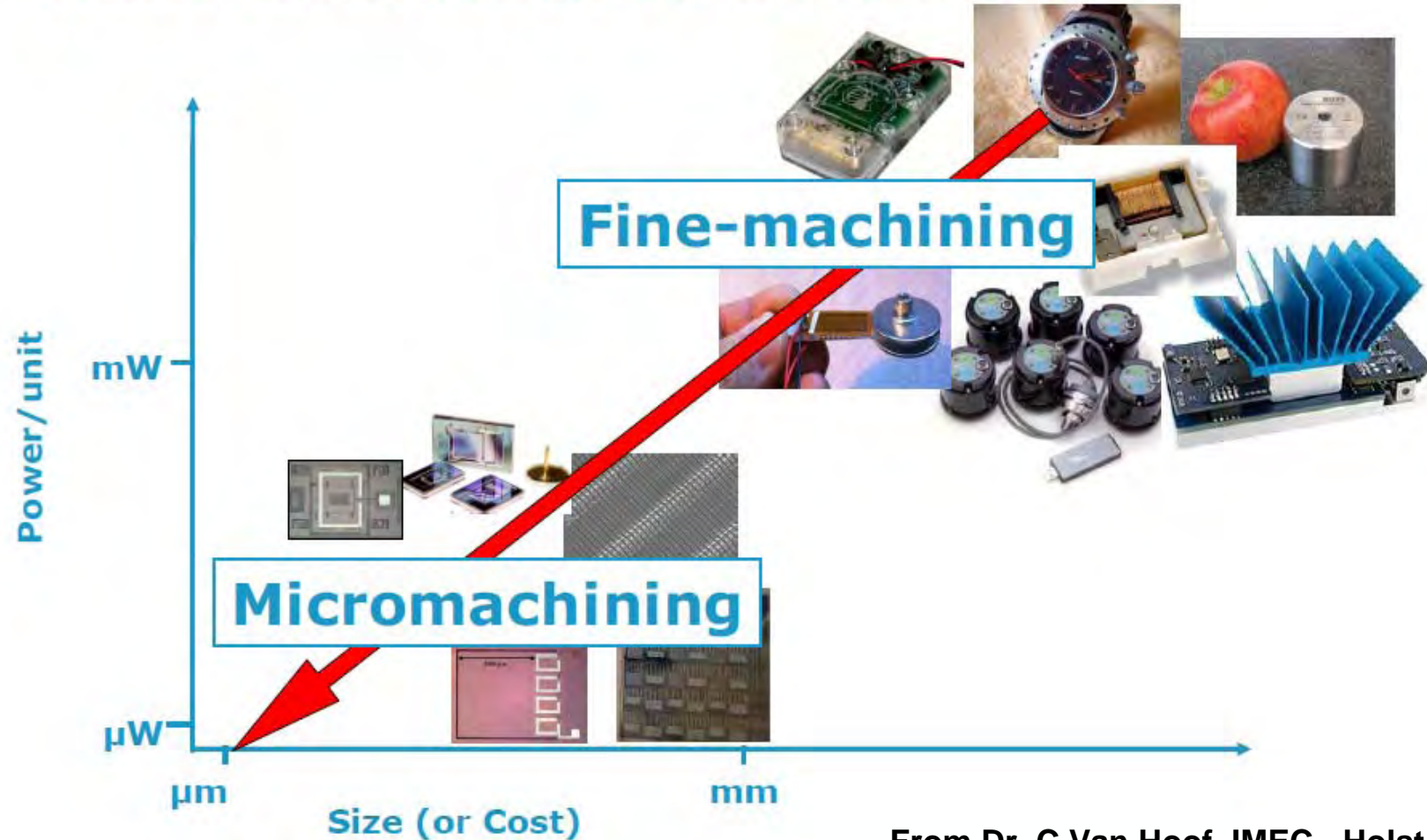


*Vullers et al, Micropower Energy Harvesting, [Solid-State Electronics](#) 53 (7) Pgs 684-693, DOI: 10.1016/j.sse.2008.12.011

From Dr. C Van Hoof, IMEC - Holst Center

Towards miniaturization

Cost reduction through Miniaturization



From Dr. C Van Hoof, IMEC - Holst Center

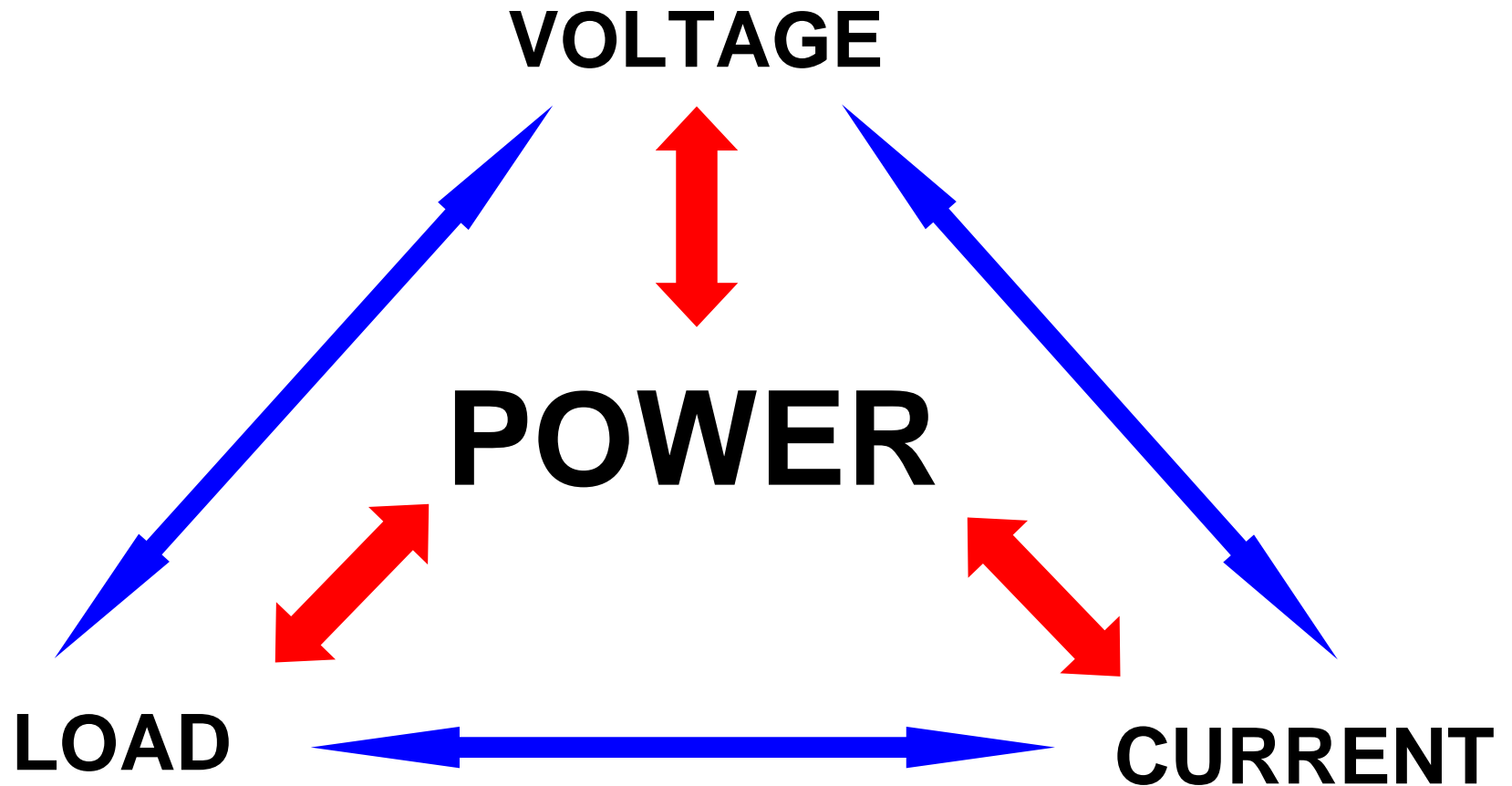
Vibration sources

Acceleration (m/s^2) magnitude and frequency of fundamental vibration mode for various sources

Vibration source	A (m/s^2)	F_{peak}
Car engine compartment	12	200
Base of 3-axis machine tool	10	70
Blender casing	6.4	121
Clothes dryer	3.5	121
Person nervously tapping their heel	3	1
Car instrument panel	3	13
Door frame just after door closes	3	125
Small microwave oven	2.5	121
HVAC vents in office building	0.2–1.5	60
Windows next to a busy road	0.7	100
CD on notebook computer	0.6	75
Second story floor of busy office	0.2	100

S. Roundy et al., Computer Communications 26 (2003) 1131–1144

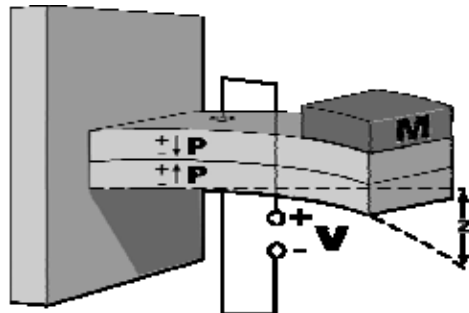
Electrical parameters of energy harvesters



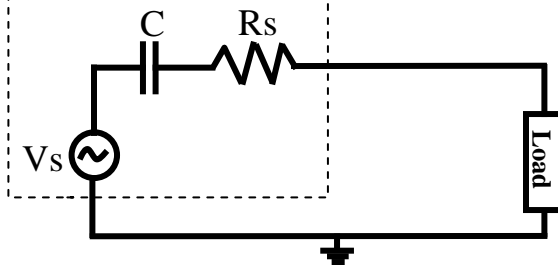
Three ways to convert vibrations

Piezoelectric

Strain in piezoelectric material causes a charge separation (voltage across capacitor)

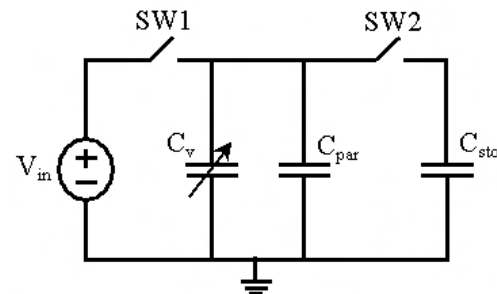
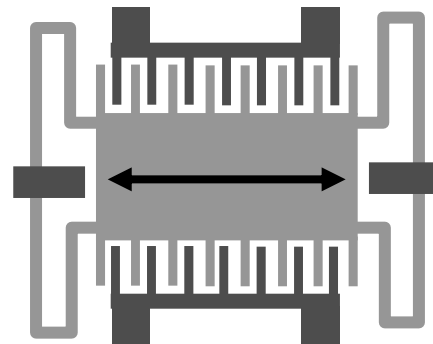


Piezoelectric generator



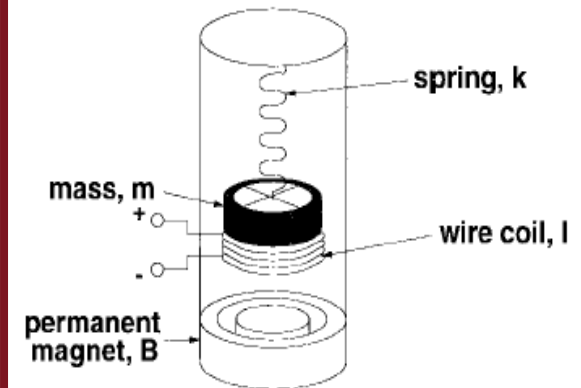
Capacitive

Change in capacitance causes either voltage or charge increase.



Inductive

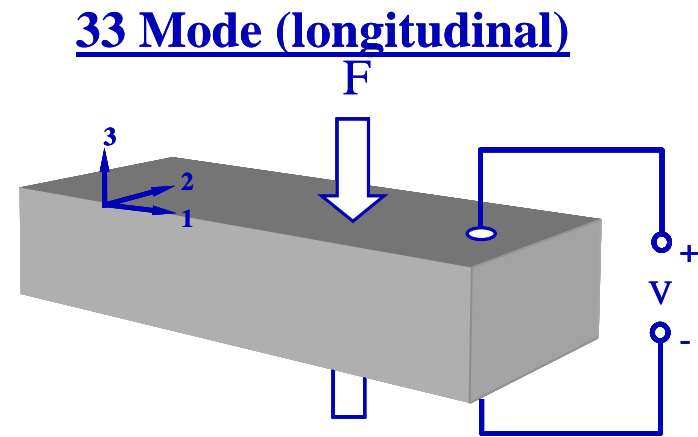
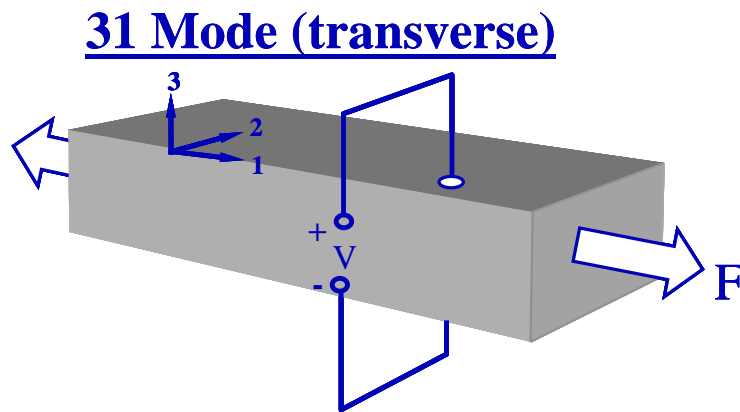
Coil moves through magnetic field causing current in wire.



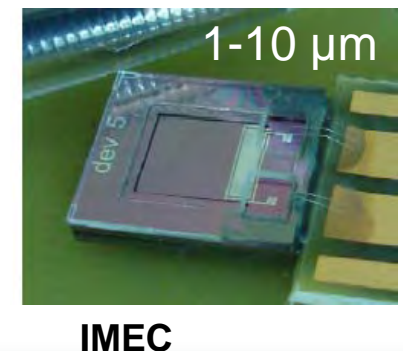
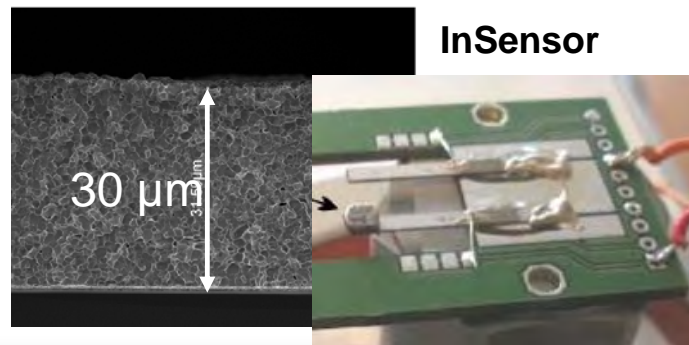
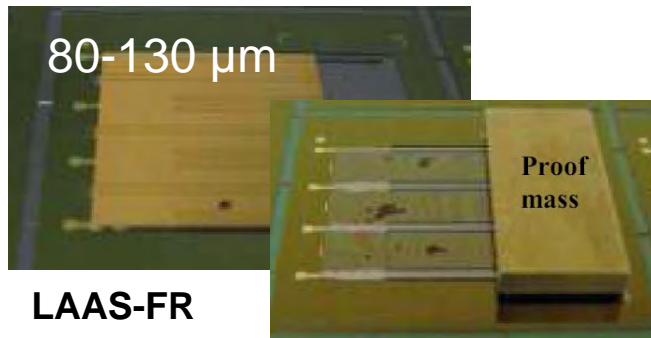
Amirtharajah et. al., 1998

Piezoelectric scavengers on silicon

- Resonant type and impact type harvesters
- d31 or d33

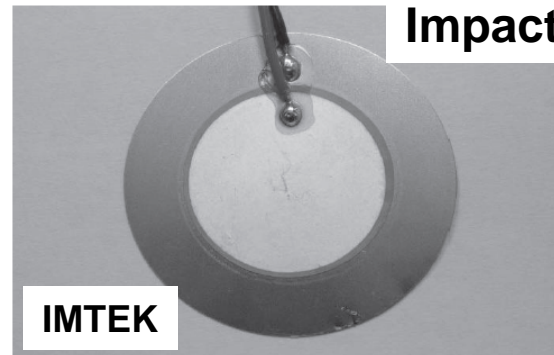
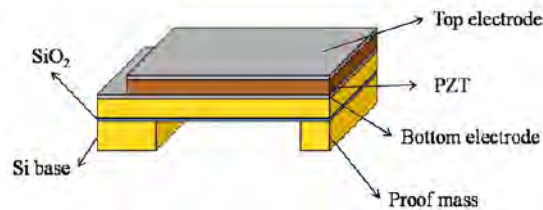


- Thick PZT sheet - Thick PZT films - Thin films (AlN, PZT)

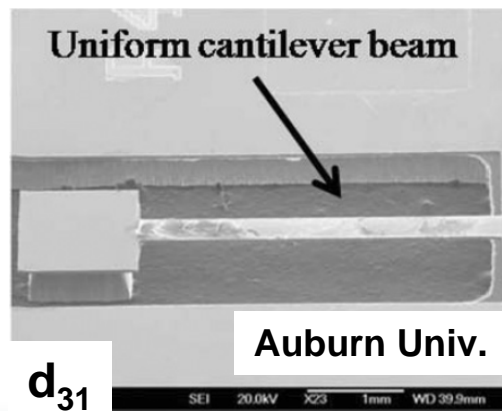
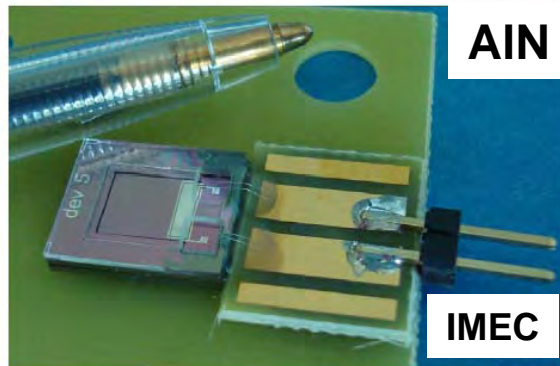
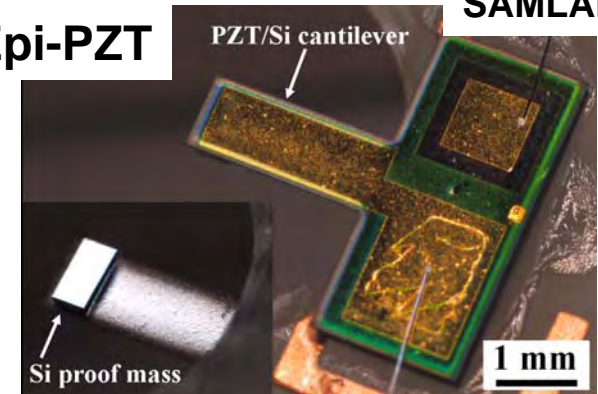


Piezoelectric micro energy harvesters

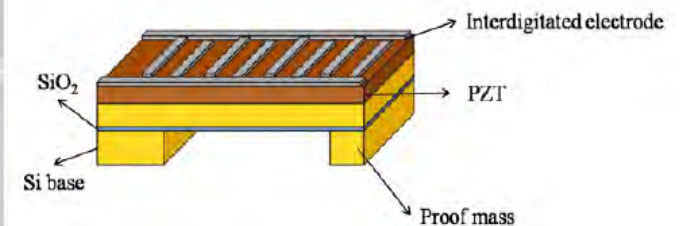
1. Impact generators
2. Resonant generators
 - d_{31} mode (transverse)
 - d_{33} mode (longitudinal)
 - AlN
 - Epitaxial films



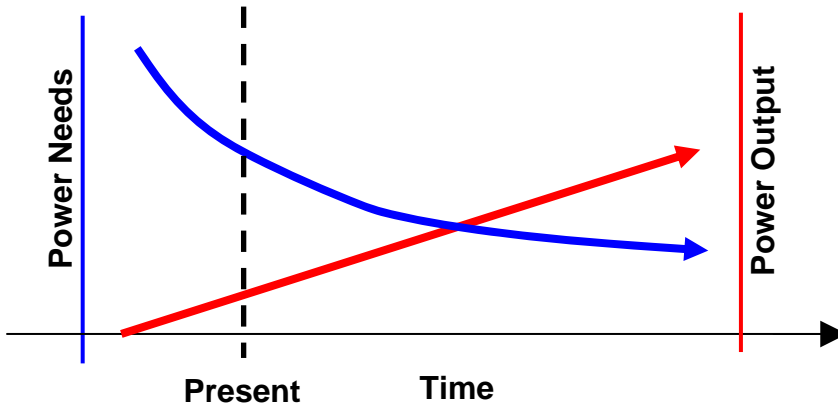
Epi-PZT



National Taiwan Univ.



MEMS power generator

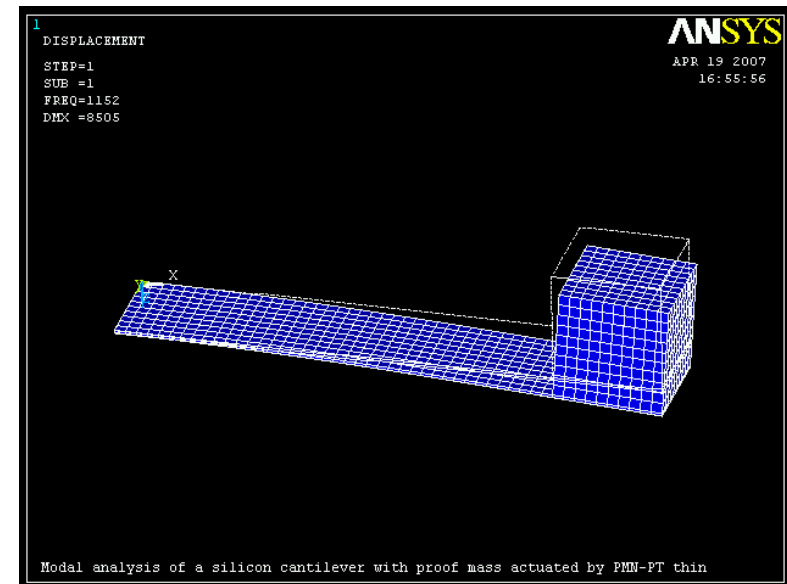


Objective

Design and fabricate a MEMS-based piezoelectric power generator for the vibrational energy harvesting

Project description

- Optimize the structure and load impedance to maximize the efficiency of the vibration-to-electricity conversion
- Develop microfabrication processes
- Study the effect of viscous air damping on the power generation
- Design a piezoelectric converter circuit
- Develop an experiment set-up for power generating test



Resonant type harvester

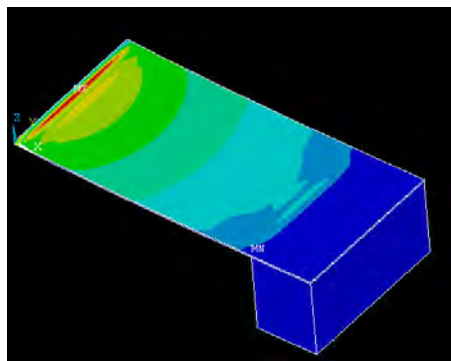
Structure design requirements

Low resonant frequency

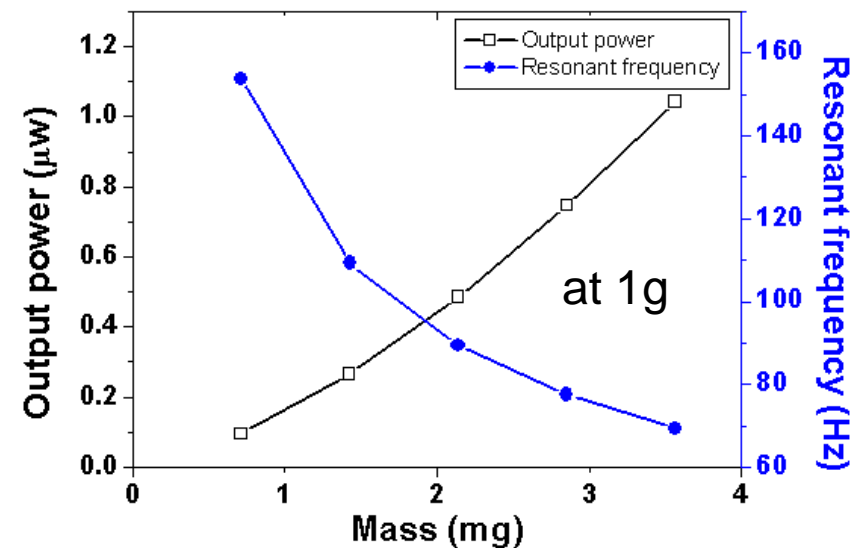
The frequency range of the ambient vibrations → 60-200 Hz

High power generation

Large stress in the PZT film → Large deflection



Modelling of PZT cantilever
with a proof mass
(1000um x 2000um)



Cantilever with a proof mass

- Heavy proof mass: low resonant frequency and high power generation
- Low damping effect
- Compactness

Analytical power model (Roundy)

$$P = \frac{1}{2\omega^2} \frac{RC_b^2 \left(\frac{1.5E_P d_{31} t_p (t_p + t_s)}{l_b^2 \epsilon} \right)^2 A_{in}^2}{(4\zeta^2 + k_{31}^2)(RC_b \omega)^2 + 4\zeta k_{31}^2 (RC_b \omega) + 4\zeta^2}$$

Measured parameters

- Frequency
- Damping ratio
- Coupling factor
- Dielectric constant
- Piezo coefficient d_{31}

- P: output power (bimorph)
- R: resistive load
- C_b : PZT capacitance
- E_p : PZT Young's modulus
- d_{31} : piezoelectric coeff.
- ϵ : dielectric constant
- t_p : PZT thickness
- t_s : silicon thickness
- l_b : cantilever length
- A_{in} : acceleration
- ζ : damping ratio
- k : coupling coeff.
- ω : angular frequency

Piezoelectric films for energy harvesters

Electrical characteristic	Figure of merit
Power generation (P_F)	e_{31}^2 / ϵ_r
Voltage generation (V_F)	e_{31} / ϵ_r
Current generation (I_F)	e_{31}



High piezoelectric coefficient
Low dielectric permittivity

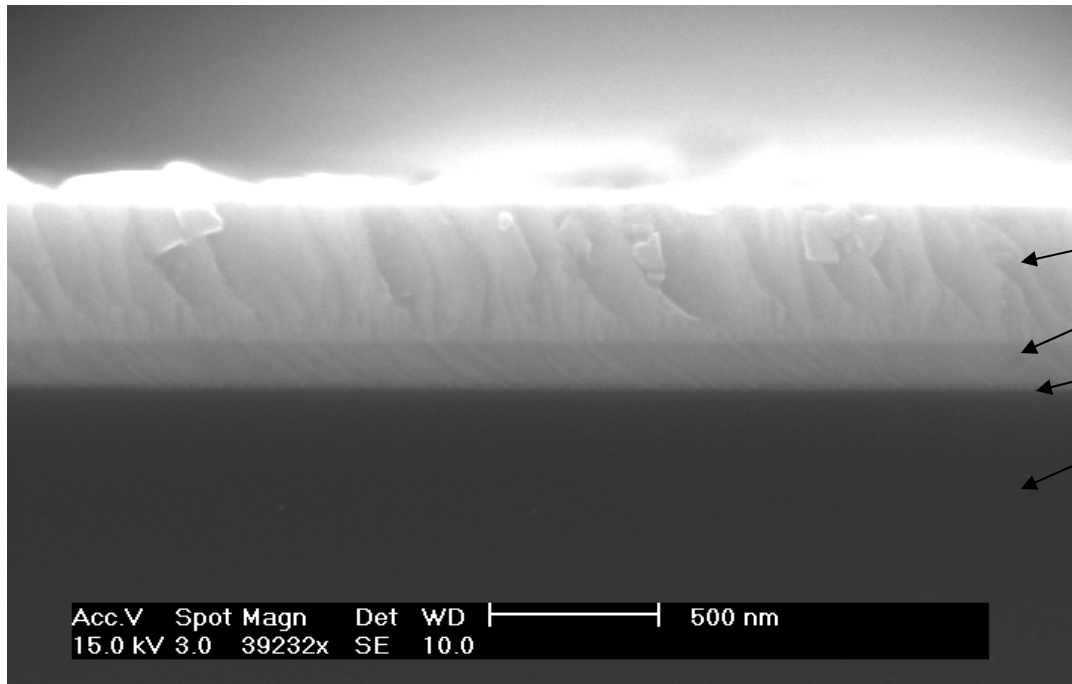
Piezo material	$-e_{31}$ (Cm ⁻²)	ϵ_r	P_F	V_F	I_F
AlN*	1.05	10.5	0.11	0.100	1.05
Poly-PZT (53/47)*	12	900	0.16	0.013	12
Epi-PZT (20/80)**	18.2	100	3.31	0.182	18.2

*S. Trolier-McKinstry and P. Muralt, J. Electroceram. **12**, 7 (2004)

**Measured data



Epi Piezo MEMS Harvester

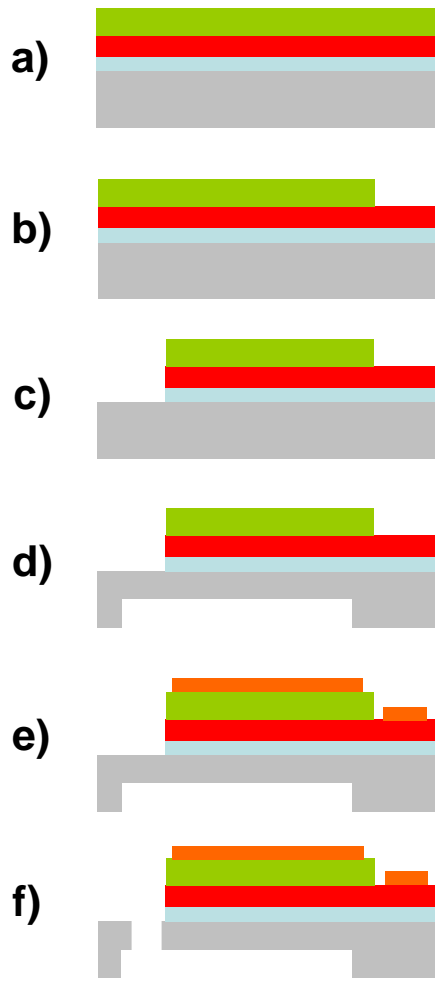


Single crystalline piezoelectric film
SRO bottom electrode
STO
Si substrate

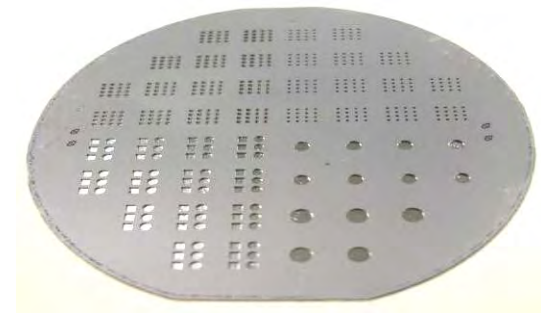
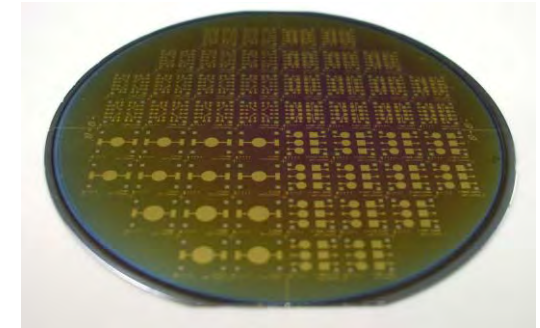
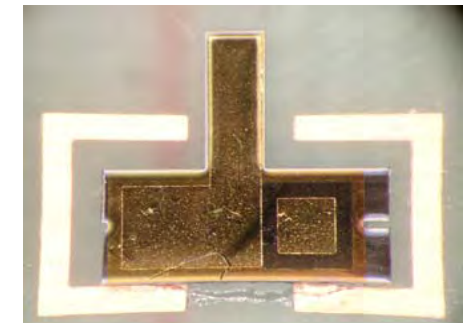
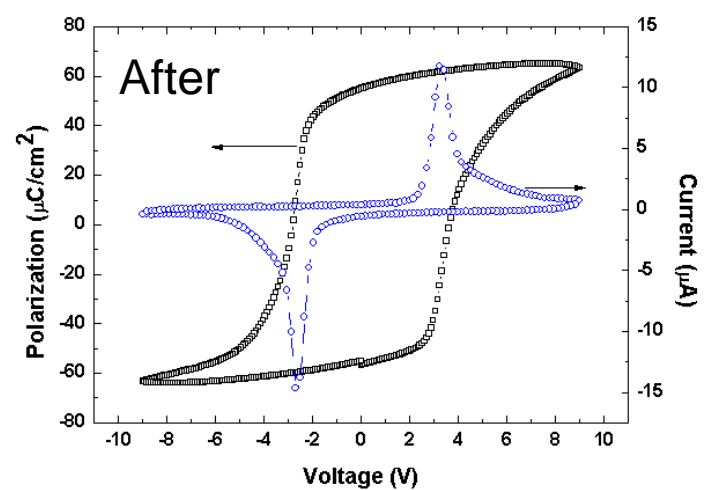
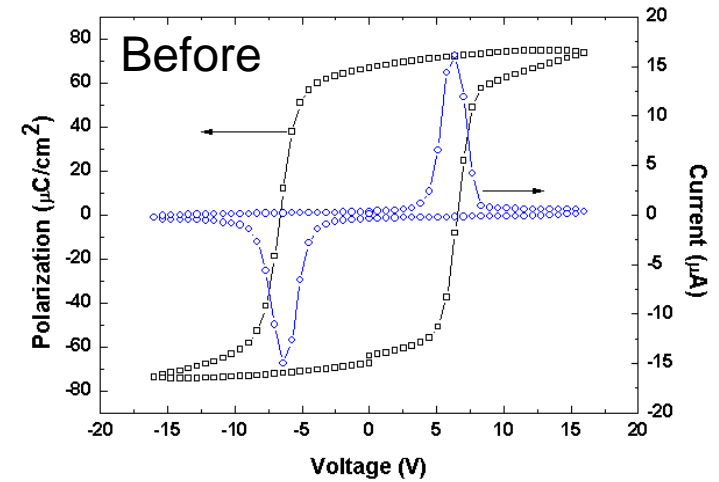
SrTiO_3 : Strontium Titanate Oxide (STO)
 SrRuO_3 : Strontium Ruthenate Oxide (SRO)

- Uniform control of the piezoelectric response over nanometer length scales
- Atomically smooth and exhibit microstructural homogeneities
- Very large piezoelectric coefficients
- Limited to maximum thickness of $0.5 \mu\text{m}$

Technology platform

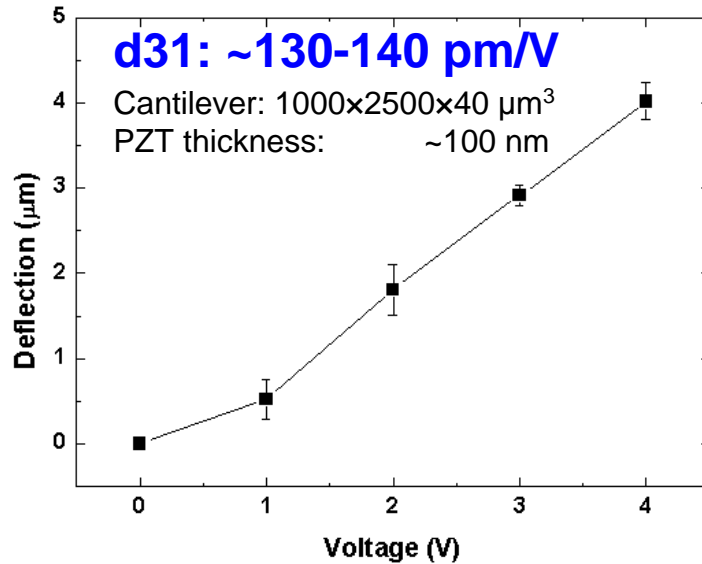


Au/Cr Piezo SRO STO Silicon



D. Isarakorn et al. JMM, 2010

Epitaxial PZT cantilevers

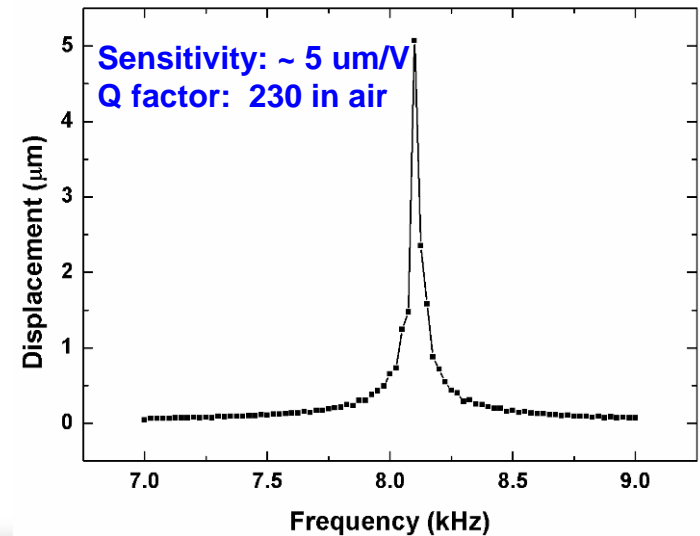
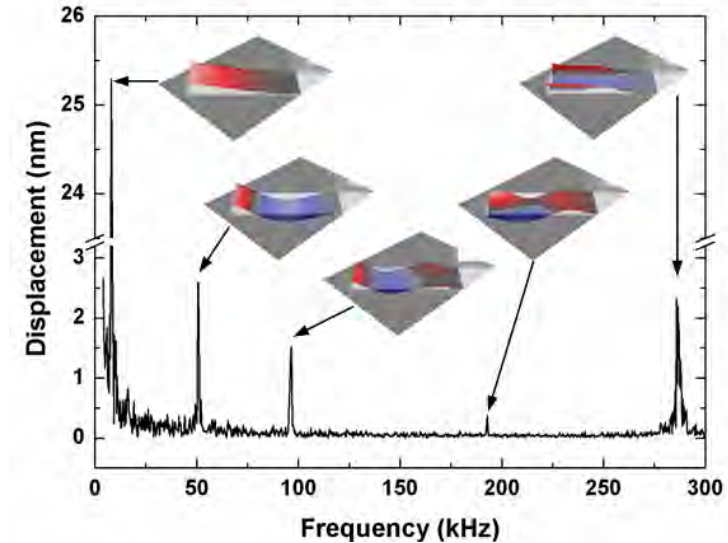


$$d_{31} = -\frac{1}{3} \frac{K}{s_s s_p h_s} \frac{\delta}{(h_s + h_p) L^2 V}$$

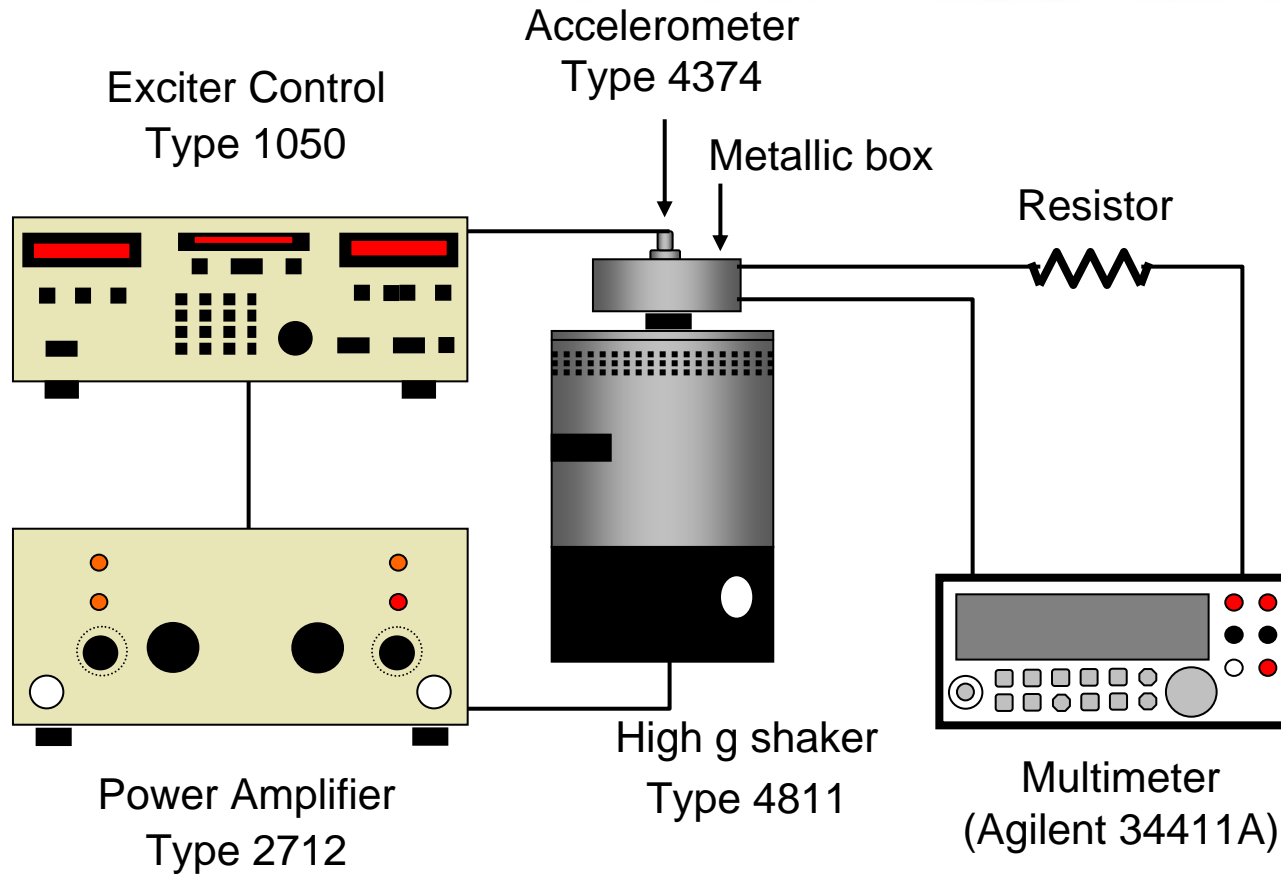
$$K = 4s_p s_s h_s h_p^3 + 4s_p s_s h_s^3 h_p + s_p^2 h_s^4 + s_s^2 h_p^4 + 6s_p s_s h_s^2 h_p^2$$

- s_s : the compliance of the Si layer ($7.7 \times 10^{-12} \text{ m}^2/\text{N}$)
- s_p : the compliance of the PZT film ($12.4 \times 10^{-12} \text{ m}^2/\text{N}$)
- h_s : the thickness of Si layer
- h_p : the thickness of the PZT film

D. Isarakorn et al. JMM, 2010



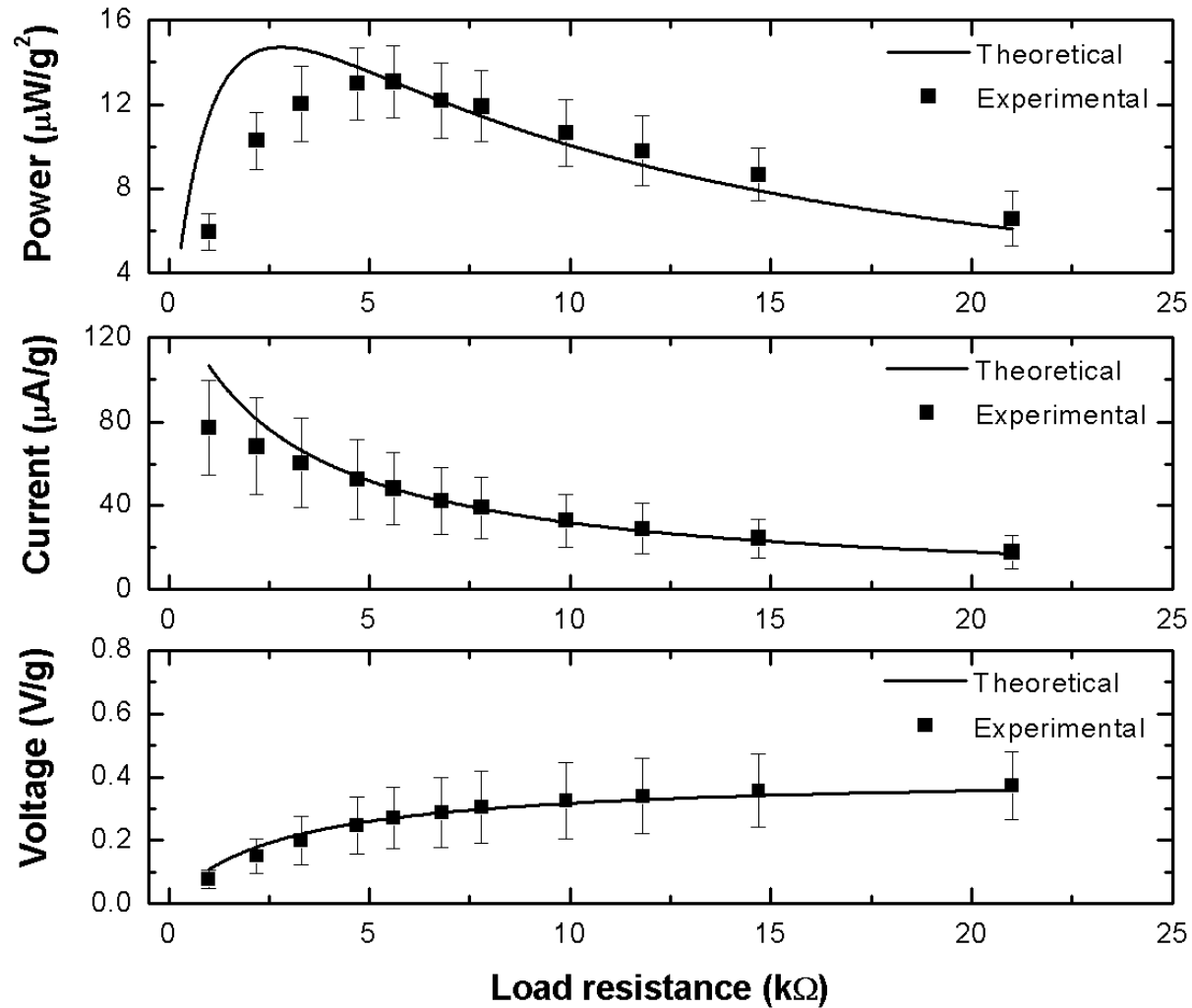
Experimental setup



Bruel & Kjaer vibration exciter system

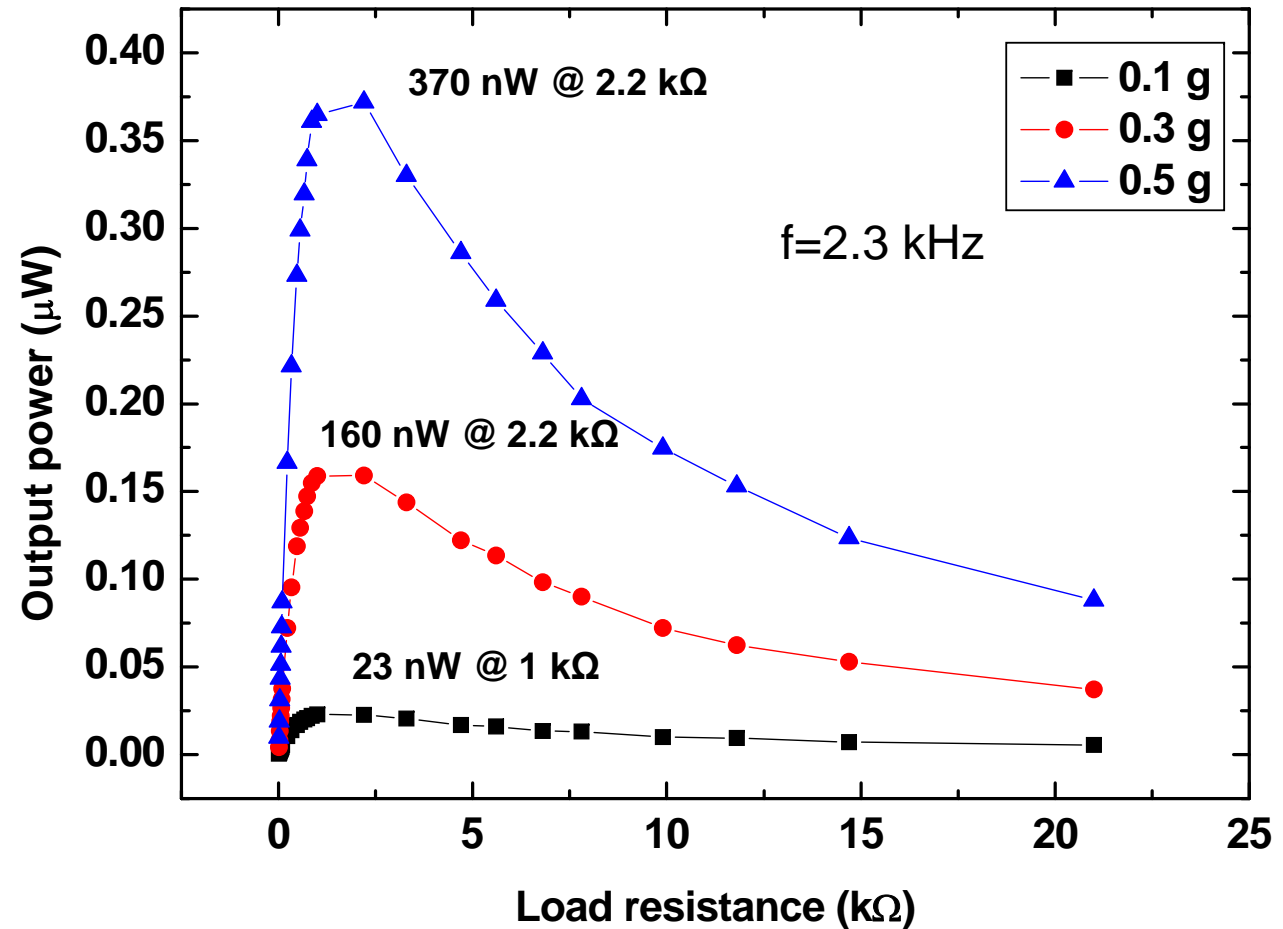
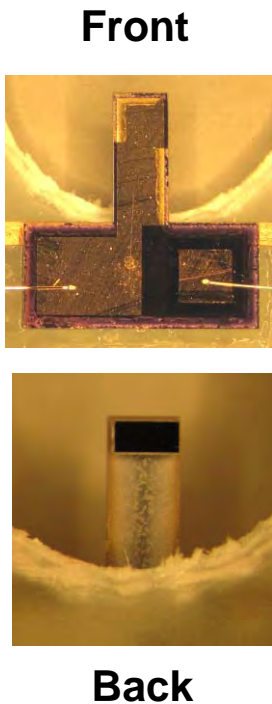
- Max acceleration 210g
- Maximum displacement 12.7 mm
- Frequency 1 Hz – 10kHz
- Frequency resolution 1.19 mHz

Experimental results



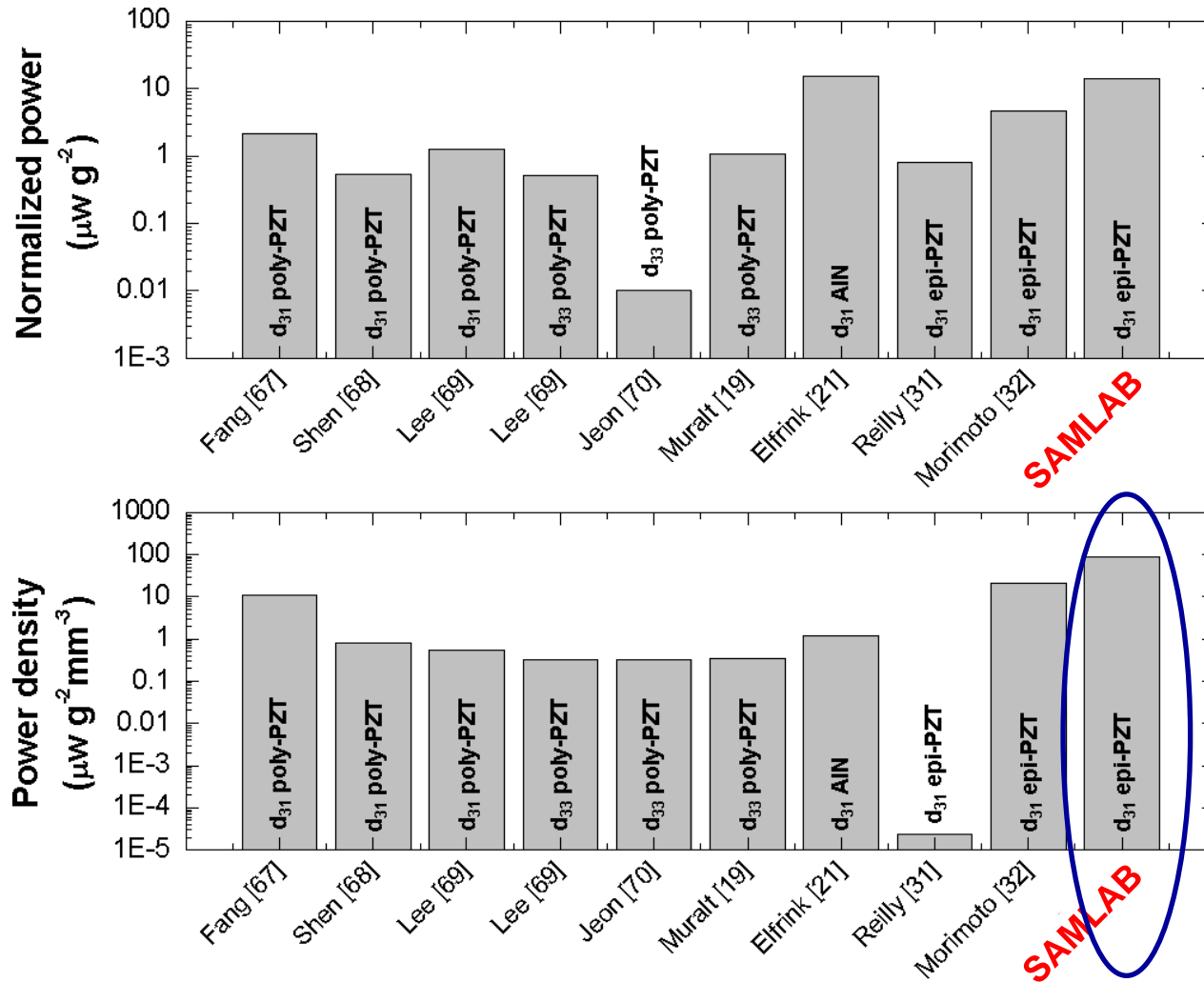
Epi PZT MEMS energy harvester

Epitaxial PZT cantilever with mass: ~500 nm PZT



D. Isarakorn et al. Proc. PowerMEMS, 2010

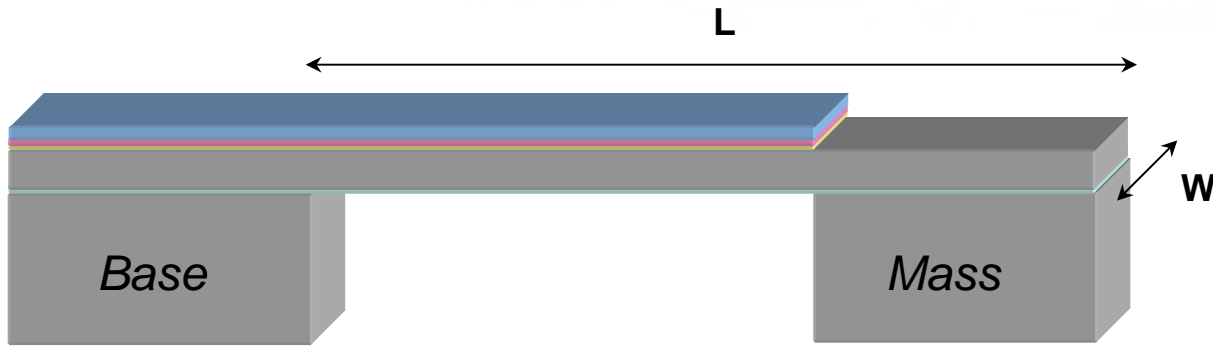
Epi Piezo MEMS Harvester - comparison



Piezoelectric energy harvester



Epi Piezo MEMS Harvester - Optimisation

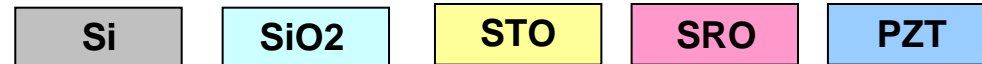


Simulation parameters

d31: 130 pC/N
 Dielectric constant: 100
 PZT thickness: 500 nm
 k31: 0.23
 Damping: 0.0004
 Acceleration: 0.2 and 0.5g

Length of the beam: 1500 μm

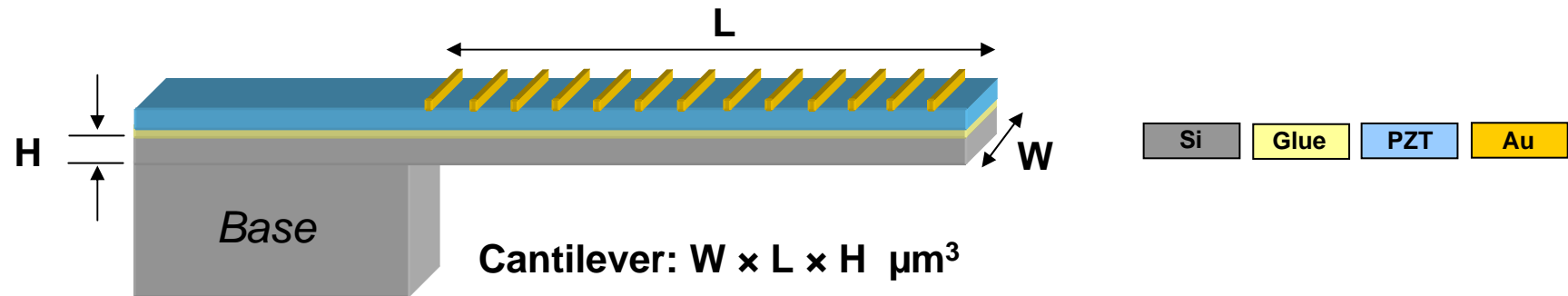
Width of the beam: 750 μm



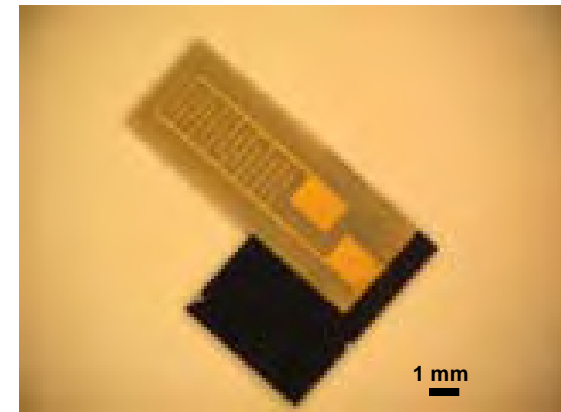
Simulation results @ 0.5g of acceleration

	P (μW)	I_{ac} (mA)	V_{ac} (mV)	f (Hz)	R_L (k Ω)	C (nF)
Typ	78	0.15	537	179	3.7	3.6

Thick PZT sheet harvesters



- Cantilever size: $3000 \times 5000 \times 50$ (100 and 150) μm^3
- Thickness of PZT sheet : $135 \mu\text{m}$
- Adhesive bonding
- Gap of interdigitated electrodes : $150 - 200 \mu\text{m}$



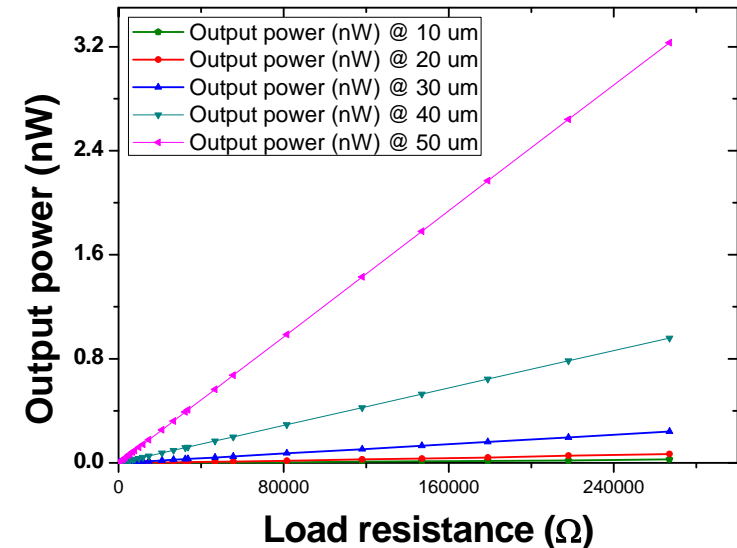
Thick PZT cantilever

Impact type harvester

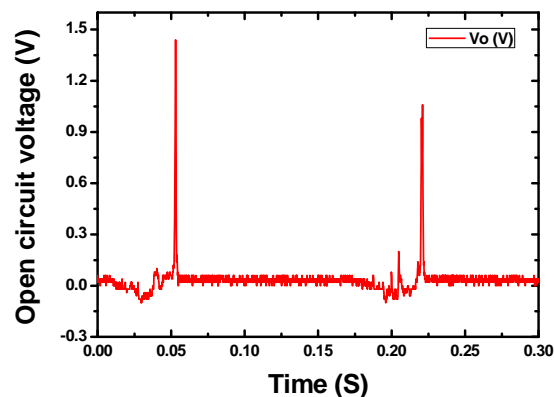
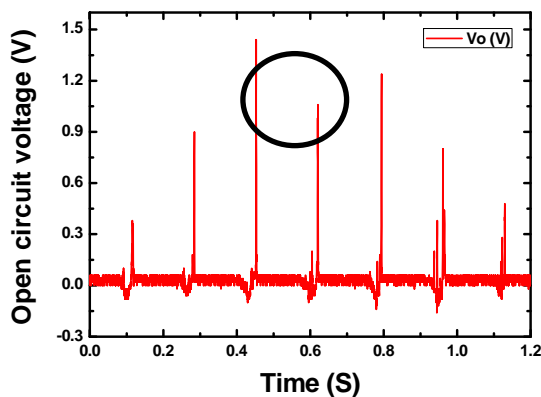
Output power measurement on impact mode

Open circuit voltage and current measurement

Amplitude (μm)	Max. V_o (Volts)	Max. I @ 10Ω (μA)
10	0.4	0.006
20	0.62	0.012
30	0.85	0.03
40	1.22	0.06
50	1.52	0.11



Open circuit voltage waveform



-Max. output power :

3.2 nW @ 267 k Ω

- Optimisation: cantilevers with different stiffness and different gaps of IDEs on piezo

Conclusions

- MEMS based energy scavengers
 - Resonant and impact types
 - Modelling, technology platforms, characterisation tools
 - Variety of materials and characteristics

- Potential for:
 - Compactness, multi-elements: Cost ???
 - CMOS integration on chip
 - Autonomous smart systems : no battery !

- Application first, solution second !!!

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- University of Yale, USA



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SWITZERLAND

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THANK YOU !

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